a laser mark printed on a surface of said package, wherein a color difference between a color of said epoxy resin and a color of a standard substance stored in a colorimeter has a value of at least 30.

6. (Amended) A semiconductor device including:

a semiconductor chip;

a package of an epoxy resin encapsulating said semiconductor chip; and

a filler that fills said epoxy resin, wherein said filler contains from 10 to 15 wt%, with respect to total filler, of a filler component having an average particle size of no more than 10 μm.

7. (Amended) A method of judging visibility of a laser mark printed on a surface of a package of a semiconductor device, the package being an epoxy resin, said method including:

measuring a color difference value between a color of the laser mark and a color of the surface of said package where the laser mark is not present, with a colorimeter; and

judging whether the color difference value is at least 10.

IN THE ABSTRACT:

Replace the Abstract with:

ABSTRACT OF THE DISCLOSURE

A semiconductor device that uses a semiconductor sealing epoxy resin composition excellent in visibility for laser marking and in fluidity characteristics. A semiconductor chip is sealed with a package of an epoxy resin. A laser mark is printed on a surface of the package. The color difference between the color of the laser mark and the color of the surface of the package where the laser mark is not present, as measured by a colorimeter, has a value of at least 10.